TOSHIBA 2SK3126

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE (π -MOS V)

2 S K 3 1 2 6

HIGH SPEED, HIGH VOLTAGE SWITCHING APPLICATIONS

SWITCHING REGULATOR APPLICATIONS

• Low Drain-Source ON Resistance : $R_{DS(ON)} = 0.48 \Omega$ (Typ.)

• High Forward Transfer Admittance: $|Y_{fs}| = 7.5 \text{ S}$ (Typ.)

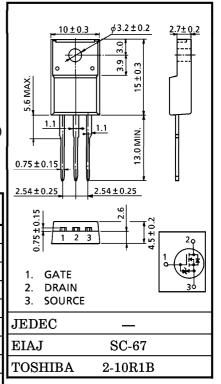
• Low Leakage Current : $I_{DSS} = 100 \,\mu\text{A}$ (Max.) ($V_{DS} = 450 \,\text{V}$)

• Enhancement-Mode : $V_{th} = 2.4 \sim 3.4 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERIS	SYMBOL	RATING	UNIT	
Drain-Source Voltage	$ m v_{DSS}$	450	V	
Drain-Gate Voltage (RG	${ m v_{DGR}}$	450	V	
Gate-Source Voltage	v_{GSS}	±30	V	
Drain Current	DC	$I_{\mathbf{D}}$	10	A
	Pulse	${ m I_{DP}}$	40	A
Drain Power Dissipation	$P_{\mathbf{D}}$	40	W	
Single Pulse Avalanche	EAS	222	mJ	
Avalanche Current	I_{AR}	10	A	
Repetitive Avalanche En	E_{AR}	4	mJ	
Channel Temperature	$\mathrm{T_{ch}}$	150	°C	
Storage Temperature Ra	$\mathrm{T_{stg}}$	-55~150	$^{\circ}\mathrm{C}$	

INDUSTRIAL APPLICATIONS Unit in mm



THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	R _{th (ch-c)}	3.125	°C/W
Thermal Resistance, Channel to Ambient	R _{th (ch-a)}	62.5	°C/W

Note:

- * Repetitive rating; Pulse Width Limited by Max. junction temperature.
- ** $V_{DD} = 90 \text{ V}$, $T_{ch} = 25^{\circ}\text{C}$ (initial), L = 3.7 mH, $R_{C} = 25 \Omega$, $I_{AR} = 10 \text{ A}$

This transistor is an electrostatic sensitive device. Please handle with caution.

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ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARA	ACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leaka	ge Current	I_{GSS}	$V_{GS} = \pm 25 \text{ V}, \ V_{DS} = 0 \text{ V}$	_	_	±10	μ A
Gate-Source Voltage	Breakdown	V (BR) GSS	$I_{G} = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	_	V
Drain Cut-o	ff Current	$I_{ m DSS}$	$V_{DS} = 450 \text{ V}, \ V_{GS} = 0 \text{ V}$	_	_	100	μ A
Drain-Sourc Voltage	e Breakdown	V (BR) DSS	$I_{D} = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	450	_	_	V
Gate Thresh	old Voltage	$ m v_{th}$	$V_{\mathrm{DS}} = 10 \mathrm{V}, \; \mathrm{I}_{\mathrm{D}} = 1 \mathrm{mA}$	2.4	_	3.4	V
Drain-Sourc	e ON Resistance	R _{DS} (ON)	$V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$	_	0.48	0.65	Ω
Forward Tra	ansfer Admittance	$ Y_{fs} $	$V_{DS} = 10 \text{ V}, I_{D} = 5 \text{ A}$	3.5	7.5	_	S
Input Capac	Input Capacitance		Vac - 10 V Vac - 0 V	_	1400	_	pF
Reverse Transfer Capacitance		C _{iss} C _{rss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz	_	240	_	
Output Cap	acitance	C_{oss}		_	590	_	
Switching Time	Rise Time	${ m t_r}$	$- V_{GS} = 0 \text{ V} $ $V_{GS} = 0 \text{ V} $ $V_{IN} : t_r, t_f < 5 \text{ ns}, $ $V_{DD} = 200 \text{ V} $ $V_{IN} = 10 \mu\text{s}$	_	35	_	
	Turn-on Time	t_{on}		_	50	_	ns
	Fall Time	t_f			80	_	115
	Turn-off Time	t _{off}		_	260	_	
Total Gate Charge (Gate- Source Plus Gate-Drain)		$\mathbf{Q}_{\mathbf{g}}$	$V_{DD} = 400 \text{ V}, V_{GS} = 10 \text{ V},$ $I_{D} = 10 \text{ A}$	_	35	_	nC
Gate-Source Charge		$\mathbf{Q}_{\mathbf{g}\mathbf{s}}$		_	19	_	
Gate-Drain ("Miller") Charge		$\mathbf{Q}_{\mathbf{gd}}$			16	_	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	$I_{ m DR}$	_	_	_	10	A
Pulse Drain Reverse Current	$I_{ m DRP}$	_	_		40	A
Diode Forward Voltage	${ m v_{DSF}}$	$I_{DR} = 10 \text{ A}, V_{GS} = 0 \text{ V}$			-1.7	V
Reverse Recovery Time	$\mathfrak{t}_{ extbf{rr}}$	$I_{DR} = 10 \text{ A}, V_{GS} = 0 \text{ V}$		1400	_	ns
Reverse Recovery Charge	Q_{rr}	$dI_{DR}/dt = 100 A/\mu s$	_	14	_	μ C

MARKING

